IMAPS DPC Community Member Preview – March 9, 2023

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From Different Dimensions
Mar 09, 2023 · By Trine Pierik · adeia, Ajinomoto, Amkor, ASE, AT&S, Cadence, Deca, ERS, EV Group, Evatec, finetech, Indium Corp., KLA, Micross, Mosaic Microsystems, NAMICS, NHanced, QPTechnologies, siemens, StratEdge Corporation, Techsearch International

The **19th Annual Device Packaging Conference** (DPC 2023) is scheduled for next week, March 13-16, 2023, at the WeKoPa Conference Center, with an anticipated record number in attendance. The microelectronics assembly & advanced packaging event will bring together industry engineers, researchers and top experts participating in a multi-faceted technical program and unique networking events, including:

- 3-track program with **80+ speakers**
- Poster presentations
- 4 keynote speakers from **Qualcomm, Samsung, General Motors**, and **Lightmatter**
- Panels covering both business and social value topics
- GBC Business plenary session: ***Building the Ecosystem: Transitioning from Research to Manufacturing***
- **Sold-out exhibit hall with 66 booths**
- Networking opportunities: welcome reception, exhibit hall reception, poster session happy hour, and group lunches
- Post-conference golf scramble and guided hike fund raisers

We at 3D InCites will be presenting our annual 3D InCites Awards on the Tuesday morning. Francoise will be moderating the DEI panel Monday night as well as conducting podcast interviews Tuesday and Wednesday. Wednesday evening is the annual poster session and DEI fundraiser event, where you can see this year's mural in completion, and Thursday we invite you to join us for a hike with proceeds benefiting our DEI fund. It's shaping up to be another very busy DPC!

Here is a list of who, where and what our community members will be up to…

Community Member Booths:

Finetech 1

MRSI Mycronic 14

TechSearch International 22

Micross 24

KLA 25

Cadence 27

Evatec 25

Amkor Technology 38

DECA 39-40

NAMICS 41

QP Technologies 43

EV Group 44

ASE Group 47-48

Siemens 49

Adeia 50

StratEdge 51

3D InCites 52

Indium 56

ERS 63

Monday, March 13, 2023
Professional Development Courses

- 8:00AM-10:00AM
    - PDC1: *The Evolution of Flip Chip Package Technology,* Mark Gerber, ASE US, Inc.
- 10:30AM-12:30PM

- PDC4: *Introduction to Fan-Out Wafer Level Packaging (FOWLP),* Beth Keser, IMAPS President
- 1:00PM-3:00PM
  - PDC9: *System-in-Package (SiP) – System Solutions Through Miniaturization,* Mark Gerber, ASE US, Inc.
- 3:30PM-5:30PM
  - PDC10: *Fan Out for Advanced Packaging Application,* John Hunt, TechSearch International
- 7:00PM-8:00PM

IMAPS/3D InCites DEI Roundtable Discussion on: ***DEI: It Takes a Village***
DEI Chair:
Robin Davis, Deca Technologies
Moderator & Podcaster:
Françoise von Trapp, 3D InCites

Tuesday, March 14

- 9:55am-10:15am

3D InCites Awards
Moderator: Francoise von Trapp, 3D InCites

Technical Tracks
Several members are chairing of each of the three Technical Tracks:

Heterogeneous 2D & 3D Integration
Mike Kelly, Amkor Technology
Fan-Out, Wafer Level Packaging & Flip Chip
Craig Bishop, Deca
Curtis Zwenger, Amkor Technology
Next Gen Applications (Automotive, 5G/6G…)
Vik Chaudhry, Amkor Technology

Notable Tuesday Sessions:
10:45am-11:15am

Scaling Interconnect Densities to Meet the Growing Demand for Chiplet Integration
Robin Davis, Deca Technologies (Tim Olson)
11:15am-11:45am

Heterogenous Integration: Simplifying the Landscape
Michael Kelly, Amkor Technology, Inc. (Dave Hiner, George Scott)
Understanding Warpage Behavior on Different Handling Platforms of FOWLP
Debbie-Claire Sanchez, ERS electronic GmbH
11:45am-12:15pm

Universal Chiplet Interconnect Express™ (UCIe™) – Building an Open Ecosystem of Chiplets for On-package Innovations
Vik Chaudhry, Amkor Technology
5G/6G MAESTRO Materials: Glass Substrates for mmWave/sub-THz Applications
Paul Ballentine, Mosaic Microsystems (Shelby Nelson)
12:15pm-12:45pm

Using M-Series with Adaptive Patterning to shrink PCB systems into System-In-Packages
Justin Locke, Siemens EDA (Robin Davis, Deca Technologies)
4:00pm-4:30pm

Performance enablement through Advanced FOPOP for Networking and Mobile
Mark Gerber, ASE Group (Nathan Whitchurch, Amkor Technology)
Advanced Insulation Materials for Next Generation High-Density Package
Shohei Fujishima, Research Institute for bioscience Products & Fine Chemicals, Ajinomoto Co., Inc.

4:30pm-5:00pm

Squaring Off with M-Series Fan-Out Technology
Clifford Sandstrom, Deca Technologies (Benedict San Jose, Deca Technologies; Jen-Kuang Fang, Ping-Feng Yang, Sheng Feng-Huang, Ping-Ching Shen, ASE)
5:00pm-5:30pm

Novel IR Laser Debonding for Heterogeneous Integration and 3D Integration
Thomas Uhrmann, EV Group (Peter Urban, Markus Wimplinger, Boris Povazay, Julian Bravin, Bernd Thallner)

Tuesday Evening Panel Discussion

- 6:30pm-8:00pm (ROOM 107-108)

PACKAGING CHIPLETS: OPPORTUNITIES AND REMAINING CHALLENGES
Moderator:
E. Jan Vardaman, President and Founder, TechSearch International, Inc.
Panelists:
SP Jeng, TSMC | Director, Advanced Packaging Technology & Service Group
Mike Kelly, Amkor Technology | VP, Advanced Packaging Development and Integration
Choon Lee, JCET Group | Chief Technology Officer
Ravi Mahajan, Intel Corp. | Intel Fellow
Chris Scanlan, Besi Switzerland AG | Senior Vice President Technology

Wednesday, March 15
Technical Tracks
Notable Wednesday Afternoon Sessions:
2:00pm-2:30pm

D2W Hybrid Bonding using high accuracy carrier solutions for 3D System Integration
Thomas Uhrmann, EV Group (Jürgen Burggraf, Mariana Pires, EV Group; Chun Ho Fan, Hoi Ping Ng, Ming Li, ASMPT)
2:30pm-3:00pm

High-yield Fabrication of Thin Glass Interposers
Shelby Nelson, Mosaic Microsystems, LLC (David Levy, Kyle Liddle, Patrick Borrelli)
Advanced IC Substrates for Heterogeneous Integration
Markus Leitgeb, AT&S (Venkata Mokkapati, Rozalia Beica)
5:00pm-5:30pm

Creating Systems from Chiplets – Next Generation Integration Driven by Hybrid Bonding
Robert Patti, NHanced Semiconductors,Inc.
5:30pm-6:00pm

Hybrid Bond Interconnect for Advanced Packaging Solutions
Thomas Workman, Adeia Inc. (Gill Fountain, Laura Mirkarimi, Guilian Gao, Jeremy Theil, Bongsub Lee)
Optimizing New Power Switch Technology Using Flip-Chip Assembly
Sam Sadri, QP Technologies (Jiankang Bu, Ideal Power)

IMAPS POSTER SESSION HAPPY HOUR & 3D InCites DEI FUND NIGHT
Wednesday 6-8pm on the Patio

Thursday, March 16
HIKE FOR DEI, Sponsored by KLA

If you're not participating in the golf tournament, why not join us for a guided, afternoon hike in the nearby McDowell Sonoran Preserve? All proceeds benefit the 3D InCites DEI Fund, established to help tech start-ups owned by women and under-represented minorities grow and thrive. Sign up here.
When: Thursday, March 16 from 12:30pm-4pm

https://www.3dincites.com/2023/03/imaps-dpc-community-member-preview/